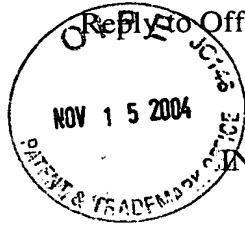


Appl. No. 09/806,401  
Amtd. Dated November 10, 2004  
Reply to Office Action of September 2, 2004



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Harry Hedler *et al.*

Application No. : 09/806,401

Filed : October 22, 2001

Title : ELECTRONIC MODULE, ESPECIALLY A MULTICHIP MODULE, WITH MULTI-LAYER METALLIZATION AND CORRESPONDING PRODUCTION METHOD

Group/Art Unit : 2827

Examiner : David E. Graybill

Docket No. : KSN0012

Box Responses - RCE  
Honorable Commissioner for Patents  
Washington DC 20231

**AMENDMENT**

Examiner:

Please amend the above-identified Application as indicated in the listing of the claims beginning on page 2. Applicants request re-examination of the pending application based upon the claim amendments and the remarks beginning on page 4.